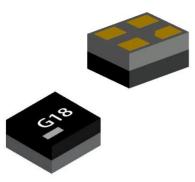


(2.3~5.5)V Input, 0.6A Output,DC-DC Ceramic Substrate Buck Module, Efficiency up to 93.5%



2 Applications

- Industrial control
- Medical imaging equipment
- Telecommunications and network applications
- Alternative to linear regulators (LDO)
- Miniaturized applications

1 Features

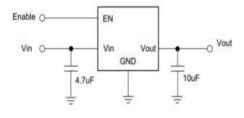
- Integrated power inductor on ferrite ceramic substrate, ultra-small footprint (2.5mm × 2.0mm)
- Shielded structure, low EMI noise
- Integrated capacitors in a single-package plastic encapsulation, providing high reliability for surface mount applications
- Synchronous rectification technology achieves high efficiency
- Automatic PFM/PWM Mode Switching Function
- Uses low-ripple PFM mode under light load conditions
- Achieves 2% voltage accuracy over the full load current range
- Wide input voltage range:2.3V~5.5V
- Maximum Load Current: 600mA
- Fixed Output Voltage: 1.2V to 3.3V (Factory Settings)
- Internal Soft Start and Overcurrent Protection

3 Description

The UDM22006 is a low-power buck DC-DC converter suitable for space-constrained or noise-sensitive applications. The device features an inductor-embedded ferrite substrate, which reduces both radiated EMI noise and conducted noise. It also uses a plastic integrated package to enhance mounting reliability.

By adding input/output capacitors, it can be used as an alternative to an LDO. Its low noise and ease of use ensure reliable power quality. The device smoothly switches between PFM and PWM modes based on the load current. It automatically switches to PFM mode under light load conditions to extend battery life and switches to PWM mode under heavy load conditions to ensure low ripple and high efficiency. The device maintains excellent output voltage accuracy even in PFM mode, keeping the output voltage accuracy within 2% over the entire load current range (0 to 600mA).

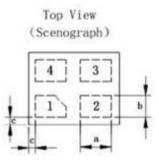
Typical Application Circuit



Vin=3.3V Efficiency VS. lout 100% 95% 90% 85% 80% Efficiency 75% 70% 65% 60% 55% Vout=1.2V Vout=1.8V 50% 0 0.1 0.2 0.3 0.4 0.5 0.6 lout,A

Note: Recommended Cin: $4.7\mu F/6.3V$, Recommended Cout: $10\mu F/6.3V$; Add more capacitance can decrease the ripple.

Pin Configuration



Top view

Pin	Symbol	Description
1	Vin	The Vin pin provides current to the internal regulator of the module.
2	EN	This is the on/off control pin of the device. Connecting this pin to GND keeps the device in the off mode. Pulling this pin to Vin enables the device with a soft start function. This pin must not be left floating. If this pin remains open, the device may turn off at 100mA output. EN = H: Device On, EN = L: Device Off.
3	Vout	Regulated output pin. Connect the output load between this pin and GND.
4	GND	Ground Pin

Ordering Information

Product Model	Input		Output	Packaging	Note
1 Todact Model	Input Range	Nominal Input	Output	T ackaying	Note
UDM22006 2.3V~5.5V			1.2V~3.3V	3000pcs/roll	

Note: Output voltages available: 1.2V, 1.35V, 1.5V, 1.6V, 1.8V, 2.1V, 2.4V, 2.5V, 3.3V. For other custom voltages, please contact us for additional customization.

Electrical Characteristics

Absolute Maximum Ratings	Conditions	Minimum Value	Nominal Value	Maximum Value	Units
Input Voltage V_{IN}, EN		-0.3		6	V
Vsw		-0.3		V _{IN} +0.3	V
Output Voltage V _{OUT}	Factory set, fixed output voltage	1.2		3.3	V
Storage Temperature		-40		+150	°C
Electrical characteristics	Conditions	Minimum Value	Nominal Value	Maximum Value	Units
Input Voltage Range		2.3		5.5	V
Input Undervoltage Lockout Threshold			2	2.25	V
Input Undervoltage Lockout Hysteresis			150		mV
Minimum Start-Up Voltage		2.3			V
Quiescent current	No Load, Not Switching		18		μA
Shutdown current	EN = GND		0.1	1	μA
Switching Frequency			10		MHz
Efficiency	V_{IN} =3.3V , V_{OUT} =1.8V , I_{OUT} =0.45A		93.5		%
EN Threshold (On)		1.2			V
EN Threshold (Off)				1.07	mV
Maximum Duty Cycle				100	%
Soft-Start Time			280		μs
Line regulation	lout=0.6A,2.3V < VIN< 5.5V			±1	%
Load regulation	V_{IN} =3.3V , V_{OUT} =1.8V,0A < $I_{OUT} \le 0.6A$			±1.5	%
Ripple and noise	V _{IN} =3.3V, V _{OUT} =1.8V, I _{OUT} =0.45A, C _{out} =10uF,Bandwidth:20MHz		15		mV
Dynamic load response	50-100% ILOAD,di/dt=2A/µs C _{out} =10 uF		25		mV

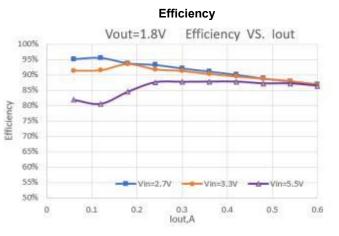
Electrical Characteristics(continued)

Structural Characteristics	Conditions	Minimum Value	Nominal Value	Maximum Value	Units
Dimensions	2.5mm×2.0mm×1.35mm 2.5mm×2.0mm×1.00mm				mm
Weight			0.023		g
Environmental Adaptability	Conditions	Minimum Value	Nominal Value	Maximum Value	Units
Operating Temperature (Case Temperature)		-40		125	°C
High-Temperature Storage (Ambient Temperature)	+125℃, 48h				
High-Temperature Operation (Ambient Temperature)	+85°C, 24h; Low Input Voltage, Nominal Input Voltage, High Input Voltage, 8 hours each; V _{IN} =60V, V _{OUT} =12V, I _{OUT} =2.4A				
Low-Temperature Storage (Ambient Temperature)	-55℃, 24h				
Low-Temperature Operation (Ambient Temperature)	-40 ℃,24h; Low Input Voltage, Nominal Input Voltage, High Input Voltage, 8 hours each;				
Humid Heat	High-Temperature and High-Humidity Stage: 60℃,95%; Low-Temperature and High-Humidity Stage: 30℃,95%; 10 cycles of 24h each				
Temperature Shock	High Temperature: 125℃, Low Temperature: -55℃, High and low temperatures of one hour each for a cycle, a total of 32 cycles of testing				

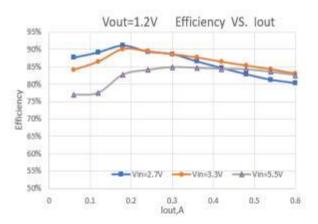
Note: Stress above the values listed in the "Absolute Maximum Ratings" section may cause permanent damage to the device. Exposure to any absolute maximum rating condition for extended periods may affect the reliability and lifespan of the device.

Typical characteristics

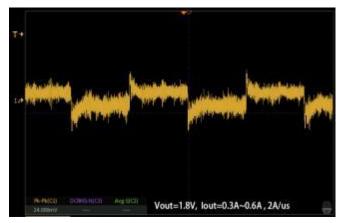
Unless otherwise noted, test conditions are T_ambient = 25 $^\circ\!\!\mathbb{C}_{\,\circ}$

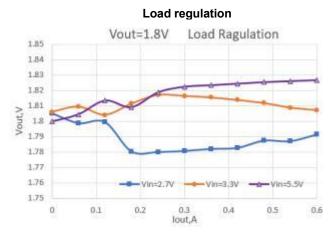


Efficiency



Vout=1.8V Dynamic Response

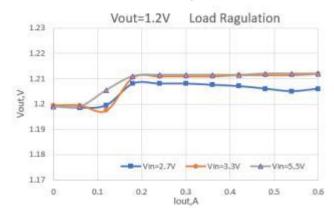




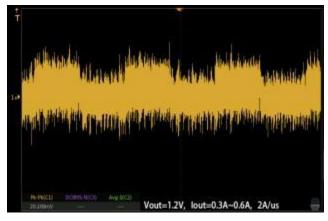
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Load regulation



Vout=1.2V Dynamic Response



Operation

summary

The UDM22006 is a DC-DC buck power module with synchronous rectification control, featuring an embedded inductor on a magnetic ceramic substrate. It integrates a control IC, power MOSFETs, and filtering capacitors. The module requires only input and output capacitors for operation. It has a small footprint and high power density, making it particularly suitable for applications with limited board space.

It uses a ceramic substrate with a shielded structure, providing excellent EMI resistance. It combines high reliability, good thermal conductivity, and low temperature rise.

The device smoothly switches between PFM and PWM modes based on the load current. Under light load conditions, it automatically switches to PFM mode to extend battery life. Under heavy load conditions, it automatically switches to PWM mode to ensure low ripple and high efficiency. The device maintains good output voltage accuracy even in PFM mode.

It maintains 2% output voltage accuracy over the entire load current range (0 to 600mA).

Internal Soft-Start (SS)

The soft start function is designed to prevent inrush current during module startup. The UDM22006 has an integrated soft start feature: when the module is enabled, the typical soft start time is 280µs.

Active Output Capacitor Discharge

After EN is turned off, an internal resistive discharge path is provided between the output capacitor and ground.

Overcurrent Protection and Short Circuit (OCP)

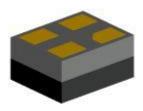
The UDM22006 features cycle-by-cycle current limit protection. When the inductor current peak exceeds the internal peak current limit threshold, the upper transistor is turned off and a counter begins. After about ten consecutive occurrences, the device will enter the EN off state. Approximately 1.5ms later, EN will turn on again, and the power module will perform a soft start.

Over temperature Shutdown Protection (OTP)

To prevent damage from overheating, the UDM22006 stops switching when the internal chip temperature exceeds 150°C. Once the temperature falls below the threshold (typically 130°C), the module resumes operation.

PACKAGE DESCRIPTION

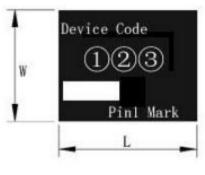




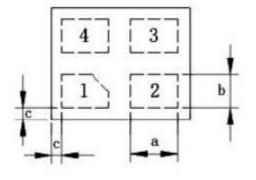
Side View



Top View

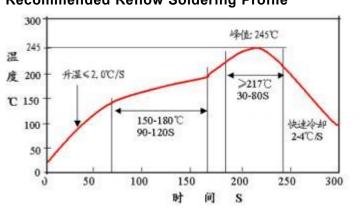


Top View (Scenograph)



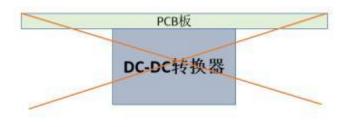
Symbol	Dimension (MM)
L	2.5±0.2
W	2.0±0.2
т	1.35Max or1.1Max
а	0.85±0.1
b	0.60±0.1
С	0.15±0.15

Soldering and Storage Precautions Recommended Reflow Soldering Profile



Note:

1. Due to the larger size of the module, do not place the module on the bottom side of the board during reflow soldering to avoid module drop.



 For bulk and unpackaged products, store them in a dry box (relative humidity should be kept below 10%). For products that are still in their original packaging, store them in a dry box whenever possible.

3.Before mounting, moisture-sensitive products must be baked according to strict baking conditions: bake for more than 48 hours at 125°C.

